

Specification for TFT

AFL240240A0-1.54INTM-ANO

Revision VO



Α	Orient Display
FL	TFT Type
240240	Resolution 240 x 240
A0	Serial A0
1.54	1.54", Module Dimension 35.0 x 50.0 x 5.0mm
1	IPS Display
N	Top: -20~+70°C; Tstr: -30~+80°C
Т	Transmissive
М	Normal Brightness, 300cd/m2
1	Controller <u>ST7789V</u>
ANO	SPI Interface + compatible Arduino













DOCUMENT REVISION HISTORY:

DATE	PAGE	DESCRIPTION
2020.10.3	-	First release

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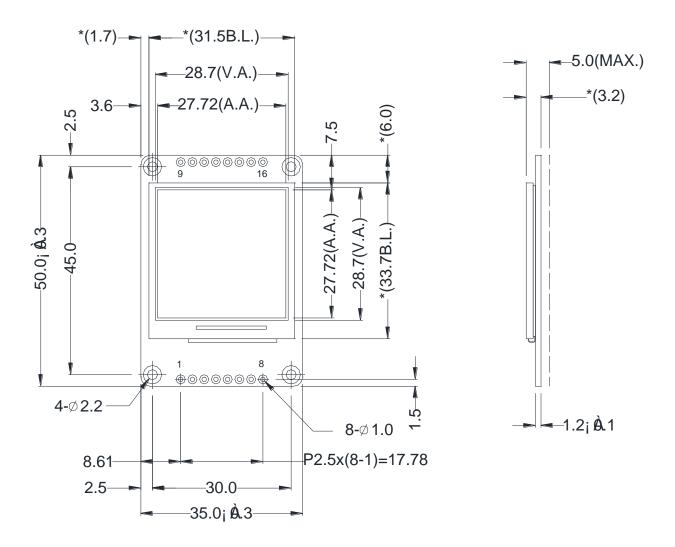
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1. General Specification

Item	Dimension	Unit			
Module dimension	35.0 x 50.0 x 5.0(MAX)	mm			
View area	28.7 x 28.7	mm			
Active area	27.72 x 27.72	mm			
Dot pitch	0.1155 x 0.1155	mm			
Number of Dots	240(RGB) x 240	dots			
LCD TYPE	TFT, Transmissive				
Top Polarizer Type	Glare				
View direction	All View				
Drive IC	ST7789V				
Interface Type	SPI 4-wires				
Backlight Type	3 White LED	3 White LED			
Touch Panel	Not Available				

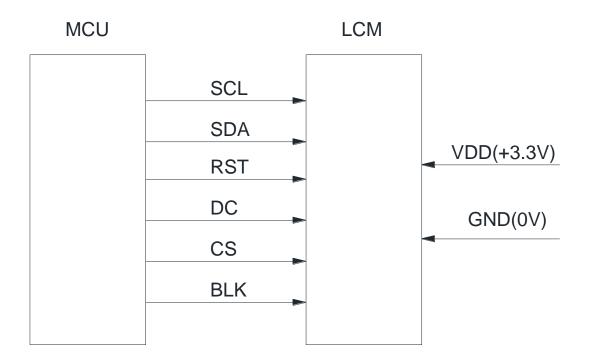
2. Mechanical Drawing



*ST7789V or equivalent

*()dimension for reference only

3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Level	Description
1	GND	0V	Ground
2	V_{DD}	3.3V	Supply Voltage for logic
3	SCL	H/L	Serial Clock
4	SDA	H/L	Serial Data
5	RST	H/L	Reset, signal is active low
6	DC	H/L	H:Display data or Parameter, L:Command Data
7	CS	H/L	Chip Select, signal is active low
8	BLK	H/L	Backlight control, H:turn on ,L: turn off

5.Absolute Maximum Ratings

Item	Symbol	Min	Max	Unit
Supply Voltage	VDD	-0.3	4.6	V
Input Voltage(logic input)	V _{In}	-0.3	VDD+0.5	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Tstr	-30	80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any time. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

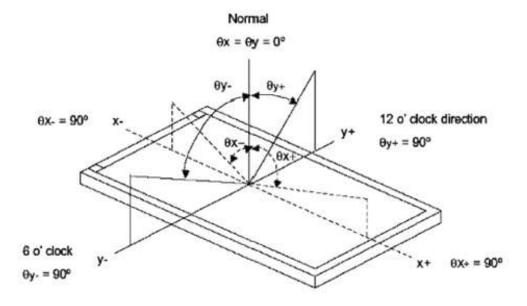
6. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage	V_{DD}	_	2.7	3.3	3.6	V
Input Voltage for Logic	V _{io}	-	0	-	3.6	V
Input High Volt.	V_{IH}	_	$0.7~V_{DD}$	_	V_{DD}	V
Input Low Volt.	$V_{\rm IL}$	_	V _{SS}	_	$0.3 \text{ V}_{\text{DD}}$	V

7. Optical Characteristics

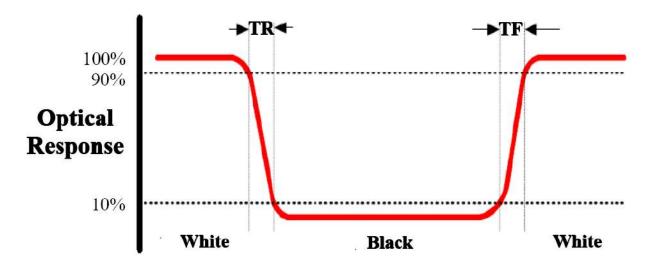
Item		Symbol	Condition	Min	Тур	Max	Unit
Luminance		L	_	300	_	_	Cd/m ²
Contrast Ratio		CR	θ=0°	_	500:1	_	_
Pagnanga Tima		T on	25℃		30		ms
Response Time		T off	25 C		30	-	1118
		Wx		0.255	-	0.330	
	White	W _Y		0.255	-	0.330	
	Red	R_X					
Color Filter		R_Y					
Chromacicity	Green	G _X					
		G_Y					
		B _X					
		B _Y					
	Цог	Θx-			80		
Viewing and	Hor.	О х+	OD: 40		80		
Viewing angle	1/0"	Өу+	CR>10		80		
	Ver.	О у-			80		
Uniformity		Un	_	80	-	—	%

Note1:Definition of Viewing Angle θx and θy :



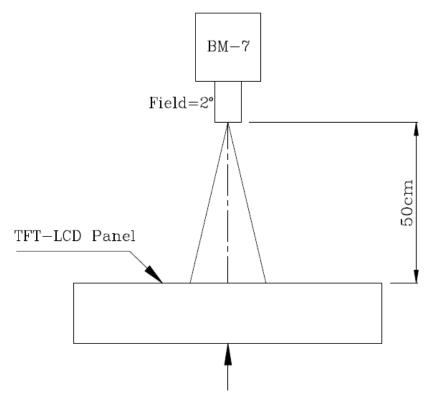
Note 2: Definition of contrast ratio CR:

Note 3: Definition of Response Time(Tr,Tf):



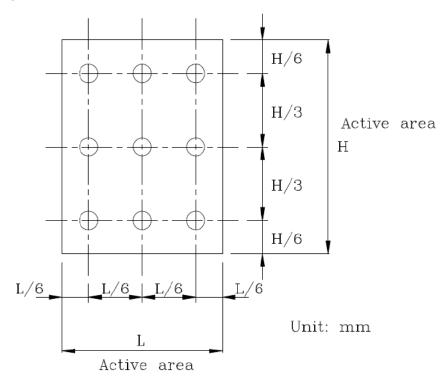
Note 4: Definition of Luminance:

1 The Brightness Test Equipment Setup
Field=2°(As measuring "black" image, field=2°is the best testing condition)

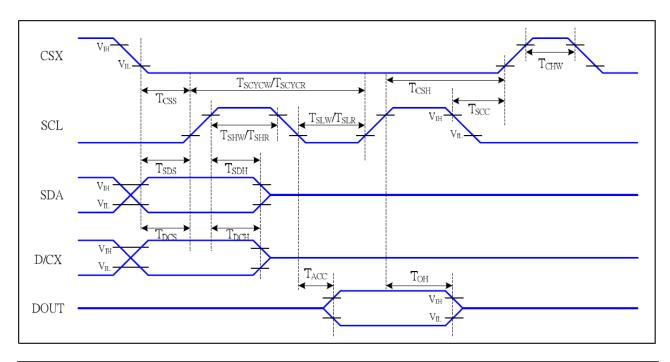


The center of the screen

2 The Brightness Test Point Setup



8. Timing Characteristics



Signal	Symbol	Parameter	MIN	MAX	Unit	Description
	T _{CSS}	Chip select setup time (write)	15		ns	
CSX	T _{CSH}	Chip select hold time (write)	15		ns	
	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (Write)	66		ns	write command ⁰ data
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	-write command & data ram
SCL	T _{SLW}	SCL "L" pulse width (Write)	15		ns	Talli
JOL	T _{SCYCR}	Serial clock cycle (Read)	1 50		ns	-read command & data
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	ram
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	Taili
D/CX	T _{DCS}	D/CX setup time	10		ns	
DICX	T _{DCH}	D/CX hold time	10		ns	
SDA	T _{SDS}	Data setup time	10		ns	
(DIN)	T _{SDH}	Data hold time	10		ns	
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF
D001	T _{OH}	Output disable time	15	50	ns	For minimum CL=8pF

9. Standard Specification for Reliability

9.1Standard Specification for Reliability of LCD Module

No	Test Item	Condition	Remarks
1	High Temperature	$Ts = +70^{\circ}C$, 96 hours	IEC60068-21:2007
	Operation		GB2423.2-2008
2	Low Temperature	$Ts = -20^{\circ}C$, 96 hours	IEC60068-2-1:2007
	Operation		GB/2423.1-2008
3	High Temperature	$Ta = +80^{\circ}C$, 96 hours	IEC60068-21:2007
	Storage		GB/2423.2-2008
4	Low Temperature	$Ta = -30^{\circ}C$, 96 hours	IEC60068-21:2007
	Storage		GB/2423.1-2008
5	Storage at High	$Ta = +60^{\circ}C$, 90% RH max,48 hours	IEC60068-2-78 :2001
	Temperature and		GB/T2423.3—2006
	Humidity		
6	Thermal	-20°C 30 min~+70°C 30 min,	Start with cold
	Shock	Change time:5min, 10 Cycle	temperature,
	(nonoperation)		End with high
			temperature,
			IEC60068-214:1984,
	EGD		GB/2423.22-2002
7	ESD	C=150pF,R=330 Ω ,5point/panel	IEC61000-42:2001
		Air: \pm 8Kv,5times;	GB/T17626.2-2006
		Contact: ± 4 Kv,5times	
		(Environment:15°C~35°C,	
		30%~60%.86Kpa~106Kpa)	
8	Vibration Test	Frequency range:10~55Hz	IEC60068-2-6:1982
		Stroke:1.5mm	GB/T2423.101995
		Sweep:10Hz~55Hz~10Hz	
		2 hours for each direction of X.Y.Z	
		(6 hours for total)	
9	Mechanical	Half Sine Wave60G	IEC60068-2-27:1987
	Shock (Non	6ms, $\pm X, \pm Y, \pm Z$	GB/T2423.5—1995
	Op)	3times for each direction	
10	Package Drop	Height:80cm,	IEC60068-2-32:1990
	Test	1corner,3 edges,6 surfaces	GB/T2423.8—1995

Note1: Ts is the temperature of panel's surface.

Note2: Ta is the ambient temperature of sample.

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
1	Current	Refer To	The current consumption should conform to the
	Consumption	Specification	product specification.
2	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
3	Appearance	Visual inspection	Defect free.

9.3MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable
	deterioration within 50,000 hours under ordinary operating and storage
	conditions room temperature (25 \pm 5 °C), normal humidity (50 \pm 10%
	RH), and
	in area not exposed to direct sun light.

10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by ODNA.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

Electrical-Optical Characteristics: According to the individual specification to test the product.

Appearance Characteristics: According to the individual specification to test the product.

Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

Test method: According to MIL-STD105E.General Inspection Level II take a

Time.

The defects classify of AQL as following:

Major defect: AQL = 0.65 Minor defect: AQL = 1.5 Total defects: AQL = 1.5

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

Purchaser should provide the data detail of non-conforming sample and the non-conforming.

After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.

If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

If any product defect be found during assembling, supplier must change the good for every defect after confirmation.

Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

Both parties should negotiate together when the following problems happen.

There is any problem of standard of quality assurance, and both sides should agree that it must be modified.

There is any argument item which does not record in the standard of quality assurance.

Any other special problem.

10.5 Standard of The Product Appearance Test

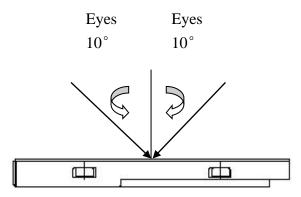
10.5.1Manner of appearance test

The test must be under $20W \times 2$ or 40W fluorescent light, and the distance of view must be at $30\pm5cm$.

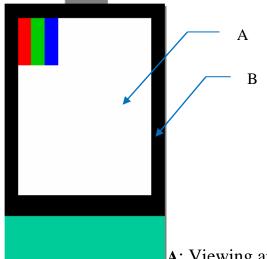
When test the model of transmissive product must add the reflective plate.

The test direction is base on around 10° of vertical line.

Temperature: 25±5°C Humidity: 60±10%RH



Definition of area:



A: Viewing area B: Outside viewing area

10.5.2 Basic principle

When the standard can not be described, AQL will be applied.

The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.

New item must be added on time when it is necessary.

10.6 Inspection Specification

NO.	Item	Criterion				AQL	
1	Electrical	1.1 Missing vertical, horizo		nt, segment	contrast defect.	0.65	
	Testing	1.2 Missing character, dot of	or icon.				
		1.3 Display malfunction.					
		1.4 No function or no displ	•		.•		
		1.5 Current consumption ex	-	luct specific	eations.		
		1.6 LCD viewing angle def	ect.				
		1.7 Mixed product types. 1.8 Flicker					
2	Black or	2.1 White and black or cold	or spots on	display ≦	0.25mm, no	1.5	
	White	more than	r spots on	aispiaj —	0.2311111, 110		
	spots	Five spots.					
	or Bright	2.2 Densely spaced: No mo	re than thre	ee spots wit	hin 3mm.		
	spots or	J 1		1			
	Color spots						
	on LCD						
	(Display						
2	only)	21D 1. A C11 . 1					
3	LCD and Touch	3.1 Round type: As following drawing					
	Panel black	$\Phi = (X+Y)/2$	a. (\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	11 04		
	spots,		Size(mm		cceptable Q'ty		
	white	→ X ← 1	$\Phi \leq 0.10$		ccept no dense		
	spots,	\rightarrow $X \leftarrow \frac{1}{2}$ Y	0.10< Ф				
	contaminati	T Y	0.20< Ф				
	on (non -	I	0.25< Ф				
	display)		0.30< Ф				
		* Densely spaced: No more			3mm.		
		3.2 Line type: (As followin	g drawing)			1.5	
			Length(Width(mn	n) Acceptable		
			mm)	** 10011(1111	Q'ty		
				W≦0.02	Accept no		
		. ±			dense		
		$L \leq 3.0 0.02 < W \leq 2$					
		→ L ← 0.05					
		2	L≦2.5	0.03 <w≦< td=""><td>2</td><td></td></w≦<>	2		
				0.08			
		0.08 <w rejection<="" td=""></w>					
		* Densely spaced: No more	than two l	ines within	3mm.		

n	Criterion			AQL
rizer oles	If bubbles are visible, judge using black spot	Size ⊕(mm)	Acceptable Q'ty	1.5
	specifications, not easy to find, must check in	Φ ≦ 0.30	Accept no dense	
	specify direction	0.30< Φ ≤ 0.5	0 0	
		0.50< Φ ≦ 1.0	0 0	
		1.00< Ф	0	
		Total Q'ty	0	
tches	Follow NO.3 -2 Line T	ype.		
oped S	k: Seal width t: Glass the L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel sur z: Chip thickness Z ≤ 1/2t 1/2t < z ≤ 2t • Unit: mm • If there are 2 or more 6.1.2 Corner crack: z: Chip thickness Z ≤ 1/2t Z ≤ 1/2t	y: Chip width Not over viewing area Not exceed 1/3k y: Chip width Not over viewing area Not exceed 1/3k y: Chip width Not over viewing area Not exceed 1/3k	ength n panels: $x: Chip length$ $x \le 2MM$ $x \le 2MM$ length of each chip $x: Chip length$ $x \le 2MM$ $x \le 2MM$ $x \le 2MM$	
1	rizer oles	rizer oles in the poles of the	rizer oles Size Φ (mm) Size Φ (mm)	rizer ples If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction $0.30 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $0.50 < \Phi \le 1.00$

NO.	Item	Criterion			AQL	
7	Glass	Symbols:			1.5	
	crack	x: Chip length y: Chip width z: Chip thickness				
	010011	k: Seal width t: Glass thickness a: LCD side length				
		L: Electrode pad lengtl				
		7.2 Protrusion over term				
		7.2.1 Chip on electrode	e pad:			
		·	L			
		W	X			
		y: Chip width	x: Chip length	z: Chip thickness		
		$y \le 0.5$ mm	$x \le 2MM$	$0 < z \le t$		
		7.2.2				
		Non-conductive portio	n:			
			₩ ^L			
		No Alba		<u> </u>		
	12					
		У				
		X		X		
		y: Chip width	x: Chip length	z: Chip thickness		
		y≦L	$x \leq 2MM$	$0 < z \le t$		
		○ If there chipped are	ea touches the ITO term	inal, over 2/3 of the ITO		
			spected according to ele			
		specifications.				
		-	be heat sealed by the cu	stomer, the alignment		
		mark must mot be damaged.				
	7.2.3 Substrate protuberance and internal crack					
		X.,	y: width x:	length		
				≦2MM		
		v				

NO.	Item	Criterion	AQL	
8	Cracked glass	No crack is allowed.		
9	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 		
10	Bezel	No scratches with W>0.1 and Length>2.5mm.		
11	COB contamination. 11.2 COB seal surface may not have pinholes through to the IC.		1.5 1.5 1.5	
		11.3 The height of the COB should not exceed the height indicated in the assembly diagram.11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places.	1.5	
		11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts.	0.65	
		11.6 The jumper on the PCB should conform to the product characteristic chart.	0.65	
12	FPC	FPC damage per IPC guidelines.(IPC-A-610) Nicks or damage along the edges of the flexible printed cir-cuitry and cutouts, providing the penetration does not exceed 50% of the distance from the edge to the nearest conductor to 2.5mm[0.1in], Whichever is less.	1.5	
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.	1.5	
		13.2 No short circuits in components on PCB or FPC.13.3 Soldering per IPC guidelines.(IPC-A-610)	1.5 0.65	

NO.	Item	Criterion			AQL
14	Touch	Symbols:			1.5
	Panel	x: Chip length y: Chip width z: Chip thickness			
	Chipped		k: Seal width t: Touch Panel Total thickness a: LCD side length		
	glass	L: Electrode pad length			
		14.1 General glass chip			
		14.1.1 Chip on panel su	urface and crack between	n panels:	
		X y k X X Y X Y X Y X Y X Y X Y X Y X Y X Y			
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦t	$\leq 1/2$ k and not over	$x \le 2MM$	
			viewing area		
		O Unit: mm			
		○ If there are 2 or more chips, x is the total length of each chip			
		14.1.2 Corner crack:			
		X Z Z Y			
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦t	$\leq 1/2$ k and not over	$x \le 2MM$	
			viewing area		
		⊙ Unit: mm			
		⊙ If there are 2 or more chips, x is the total length of each chip			
					<u> </u>

NO.	Item	em Criterion		
15	Touch Panel(Fish eye, dent and bubble on film)	(Fish dent ubble $\Phi \le 0.2$ Accept no dense $0.2 < D \le 0.4$ $0.4 < D \le 0.5$		1.5
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.		1.5
17	Touch Panel Linearity	Less than 1.5% is acceptable.		1.5
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g		1.5
19	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 		0.65 0.65 0.65

11. Handling Precaution

11.1 Handling of LCM

Avoid external shock.

Don't apply excessive force on the surface.

Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.

Don't operate it above the absolute maximum rating.

Don't disassemble the LCM.

The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

The modules should be kept in antistatic bags or other containers resistant to static for storage.

The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

Store it in an ambient temperature of $25\pm10^{\circ}$ C, and in a relative

humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.

Store it in a clean environment, free from dust, active gas, and solvent.

Store it in anti-static electricity container.

Store it without any physical load.

11.3 Soldering

Use only soldering irons with proper grounding and no leakage.

Iron: no higher than 280±10°C and less than 3 sec during hand soldering.

Rewiring: no more than 2 times.

12.PackingMethod

TBD